Session Title	Microelectronics Packaging Materials and Processing I	Session Code	Th-J1
Date and Time	2018-08-23 / 10:30 - 12:30		
Place	Room J		
Session Chair	TBA		

Th-J1-1 **10:30 - 11:00**

[Invited] Power Device Bonding Technology for Electric Vehicle Applications

Jeong-Won Yoon[1,2]
[1]KITECH, Korea, [2]Univ. of Sci. and Tech., Korea

Th-J1-2 **11:00 - 11:30**

[Invited] Thermo-Mechanical Characteristics of Solder Joints with Pillar Bump's Aspect Ratios

Hee Seon Bang, Han-Sur Bang, and Hyeong-Cheol Kim
Chosun Univ., Korea

Th-J1-3 **11:30 - 11:45**

Al-Ge Eutectic Bonding for MEMS: Managing The Presence of Native Oxide at the Interface

Victor Lumineau[1,2], Frank Fournel[1,3], and Fiqiri Hodaj[2]
[1]LETI, France, [2]Univ. Grenoble Alpes, France

Th-J1-4 **11:45 - 12:00**

Characteristics of Hi Barrier Film using Polysilazane-Dericed Silica Thin Films

Sunmin Kim[1,2], EunHae Koo[2], and Daeho Yun[1]
[1]Sungkyunkwan Univ., Korea, [2]KICET, Korea

Th-J1-5 **12:00 - 12:15**

Development of New Analysis Method with Ultrasonication for Incoming PVA Brush in Post CMP Cleaning Process

Jun-Kil Hwang[1], Jung-Hwan Lee[1], Muthukrishnan Purushothaman[1], Kwang-Min Han[1], Shohei Shima[2], Satomi Hamada[2], Hirokuni Hiyama[2], and Jun-Goo Park[1]
[1]Hanyang Univ., Korea, [2]EBARA Corp., Japan